

Radiation Hardened and SEE Hardened 12A Synchronous Buck Regulator with Current Sharing

ISL70002SEH

The [ISL70002SEH](#) is a radiation hardened and SEE hardened high efficiency monolithic synchronous buck regulator with integrated MOSFETs. This single chip power solution operates over an input voltage range of 3V to 5.5V and provides a tightly regulated output voltage that is externally adjustable from 0.8V to ~85% of the input voltage. Output load current capacity is 12A for $T_J \leq +150^\circ\text{C}$. The two ISL70002SEH devices configured to current share can provide 19A total output current, assuming $\pm 27\%$ worst-case current share accuracy.

The ISL70002SEH utilizes peak current-mode control with integrated error amp compensation and pin selectable slope compensation. Switching frequency is also pin selectable to either 1MHz or 500kHz. Two devices can be synchronized 180° out-of-phase to reduce input RMS ripple current.

High integration makes the ISL70002SEH an ideal choice to power small form factor applications. Two devices can be synchronized to provide a complete power solution for large scale digital ICs, like field programmable gate arrays (FPGAs) that require separate core and I/O voltages.

Applications

- FPGA, CPLD, DSP, CPU core and I/O voltages
- Low-voltage, high-density distributed power systems

Related Literature

- [AN1732](#) "ISL70002SEH 12A Synchronous Buck Regulator Evaluation Board User Guide"
- [AN1953](#) "ISL70002SEH Dual Phase Current Share Evaluation Board User Guide"

Features

- DLA SMD [5962-12202](#)
- Output current for a single device
 - 14A at $T_J = +125^\circ\text{C}$; 12A at $T_J = +150^\circ\text{C}$
- Output current for two paralleled devices
 - 22A at $T_J = +125^\circ\text{C}$; 19A at $T_J = +150^\circ\text{C}$
- Available in a thermally enhanced heatsink package - R64.C
- 1MHz or 500kHz switching frequency
- 3V to 5.5V supply voltage range
- $\pm 1\%$ Reference voltage (line, load, temp. and rad)
- Prebiased load compatible
- Redundancy/junction isolation: Exceptional SET performance
- Excellent transient response
- High efficiency >90%
- Two ISL70002SEH synchronization, inverted-phase
- Comparator input for enable and power-good
- Input undervoltage, output undervoltage and adjustable output overcurrent protection
- QML qualified per MIL-PRF-38535
- Full military temperature range operation (-55°C to $+125^\circ\text{C}$)
- Radiation environment
 - High dose 100krad(Si)
 - ELDRS 100krad(Si)*
 - *Level guaranteed by characterization; "EH" version is production tested to 50krad(Si).
- SEE hardness
 - SEL and SEB LET_{TH} 86.4MeV/mg/cm²
 - SEFI LET_{TH} 43MeV/mg/cm²
 - SET LET_{TH} 86.4MeV/mg/cm²

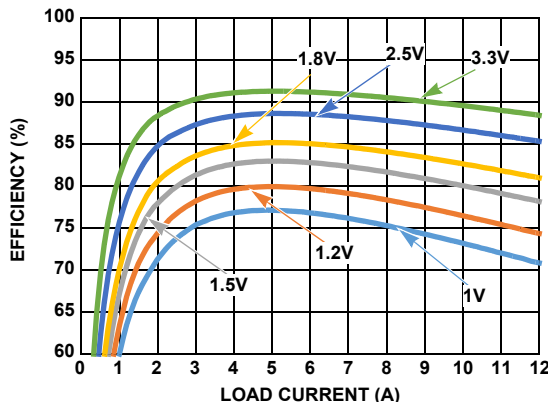


FIGURE 1. EFFICIENCY 5V INPUT, 500kHz, $T_{\text{case}} = +25^\circ\text{C}$

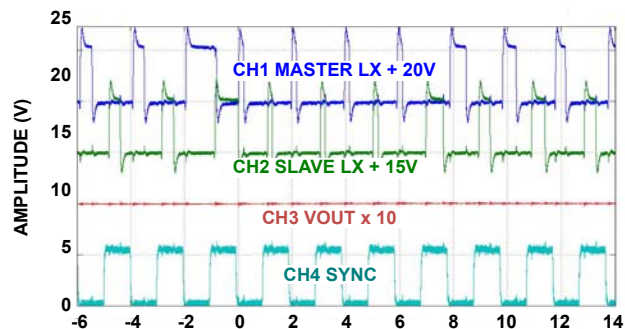


FIGURE 2. 2-PHASE SET PERFORMANCE at 86.4MeV/mg/cm²

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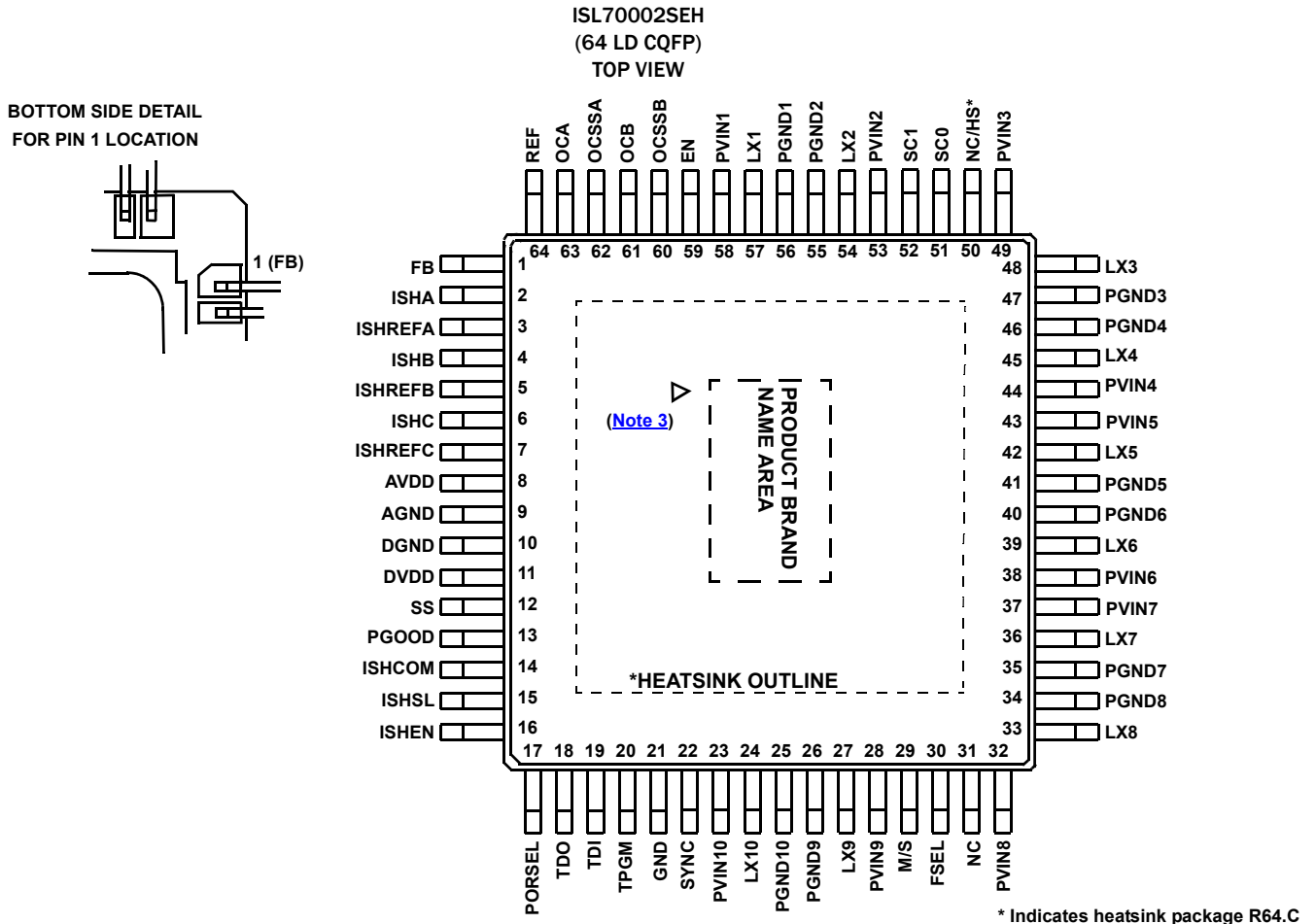
Ordering Information

| ORDERING SMD NUMBER (Note 2) | PART NUMBER (Note 4) | TEMP. RANGE (°C) | PACKAGE (RoHS Compliant) | PKG. DWG. # |
|---------------------------------|----------------------------------|---------------------|-----------------------------|----------------|
| ISL70002SEHVF | 5962R1220201VXC | -55 to +125 | 64 Ld CQFP | R64.A |
| ISL70002SEHVFE | 5962R1220201VYC | -55 to +125 | 64 Ld CQFP with Heatsink | R64.C |
| ISL70002SEHVX | 5962R1220201V9A | -55 to +125 | Die | |
| ISL70002SEHF/PROTO | ISL70002SEHF/PROTO | -55 to +125 | 64 Ld CQFP | R64.A |
| ISL70002SEHFE/PROTO | ISL70002SEHFE/PROTO | -55 to +125 | 64 Ld CQFP with Heatsink | R64.C |
| ISL70002SEHX/SAMPLE | ISL70002SEHX/SAMPLE | -55 to +125 | Die | |
| ISL70002SEHEVAL1Z | Evaluation Board | | | |
| ISL70002SEHEVAL2Z | Current Sharing Evaluation Board | | | |

NOTES:

- These Intersil Pb-free Hermetic packaged products employ 100% Au plate - e4 termination finish, which is RoHS compliant and compatible with both SnPb and Pb-free soldering operations.
- Specifications for Rad Hard QML devices are controlled by the Defense Logistics Agency Land and Maritime (DLA). The SMD numbers listed in the "Ordering Information" table must be used when ordering.

Pin Configuration



NOTE:

- The ESD triangular mark is indicative of pin #1 location. It is a part of the device marking and is placed on the lid in the quadrant where pin #1 is located.

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Pin Descriptions

| R64.A PIN NUMBER | R64.C PIN NUMBER | PIN NAME | DESCRIPTION |
|---------------------|---------------------|---------------------------------|--|
| 1 | | FB | <p>This pin is the voltage feedback input to the internal error amplifier. Connect a resistor from FB to VOUT and from FB to AGND to adjust the output voltage in accordance with Equation 1:</p> $V_{OUT} = V_{REF} \cdot [1 + (R_T/R_B)] \quad (\text{EQ. 1})$ <p>Where: V_{OUT} = Output voltage V_{REF} = Reference voltage (0.6V typical) R_T = Top divider resistor (Must be 1kΩ) R_B = Bottom divider resistor The top divider resistor must be 1kΩ to mitigate SEE. Connect a 4.7nF ceramic capacitor across R_T to mitigate SEE and to improve stability margins. If using current share, tie FB of the master to FB of the slave.</p> |
| 2, 4, 6 | | ISHA, ISHB, ISHC | <p>If configured as a current share master (ISHSL = DGND, ISHEN = DVDD), the ISHA/ISHB/ISHC pins are outputs that provide a current equal to 25 times the redundant A/B/C error amp output currents plus ISHREFA/ISHREFB/ISHREFC (nominally 100μA each). If configured as a current share slave (ISHSL = DVDD, ISHEN = DVDD), the ISHA/ISHB/ISHC pins are inputs that become the slave's redundant A/B/C error amp output current. If using current share, tie ISHA/ISHB/ISHC of the master to ISHA/ISHB/ISHC of the slave. If not using current share, tie ISHA/ISHB/ISHC to DVDD. ISHA/ISHB/ISHC are tri-stated prior to a valid POR and when ISHEN = DGND.</p> |
| 3, 5, 7 | | ISHREFA, ISHREFB, ISHREFC | <p>If configured as a current share master (ISHSL = DGND, ISHEN = DVDD), the ISHREFA/ISHREFB/ISHREFC pins provide a reference output current equal to 100μA each. If configured as a current share slave (ISHSL = DVDD, ISHEN = DVDD), the ISHREFA/ISHREFB/ISHREFC pins accept a reference input current. For a current share slave, this input current is used together with the ISHA/ISHB/ISHC current to determine the master's redundant A/B/C error amp output current. If using current share, tie ISHREFA/ISHREFB/ISHREFC of the MASTER to ISHREFA/ISHREFB/ISHREFC of the slave. If not using current share, tie ISHREFA/ISHREFB/ISHREFC to DVDD. The purpose of the reference current is to reduce the impact of external noise coupling onto ISHA/ISHB/ISHC. ISHREFA/ISHREFB/ISHREFC are tri-stated prior to a valid POR and when ISHEN = DGND.</p> |
| 8 | | AVDD | <p>This pin is the bias supply input to the internal analog control circuitry. Locally filter this pin to AGND using a 1Ω resistor and a 1μF ceramic capacitor. Locate both filter components as close as possible to the IC. AVDD should be the same voltage as DVDD and PVINx (±200mV).</p> |
| 9 | | AGND | <p>This pin is the analog ground associated with the internal analog control circuitry. Connect this pin directly to the PCB ground plane.</p> |
| 10 | | DGND | <p>This pin is the digital ground associated with the internal digital control circuitry. Connect this pin directly to the PCB ground plane.</p> |
| 11 | | DVDD | <p>This pin is the bias supply input to the internal digital control circuitry. Locally filter this pin to DGND using a 1Ω resistor and a 1μF ceramic capacitor. Locate both filter components as close as possible to the IC. DVDD should be the same voltage as AVDD and PVINx (±200mV).</p> |
| 12 | | SS | <p>This pin is the soft-start input. Connect a ceramic capacitor from this pin to DGND to set the soft-start output ramp time in accordance with Equation 2:</p> $t_{SS} = C_{SS} \cdot V_{REF}/I_{SS} \quad (\text{EQ. 2})$ <p>Where: t_{SS} = Soft-start output ramp time C_{SS} = Soft-start capacitor V_{REF} = Reference voltage (0.6V typical) I_{SS} = Soft-start charging current (23μA typical) Soft-start time is adjustable from approximately 2ms to 200ms. The range of the soft-start capacitor should be 82nF to 8.2μF, inclusive. If using current share, C_{SS} of the slave should be at least twice the C_{SS} of the master.</p> |
| 13 | | PGOOD | <p>This pin is the power-good output. This pin is an open drain logic output that is pulled to DGND when the output voltage is outside a ±11% typical regulation window. This pin can be pulled up to any voltage from 0V to 5.5V, independent of the supply voltage. A nominal 1kΩ to 10kΩ pull-up resistor is recommended. Bypass this pin to DGND with a 10nF ceramic capacitor to mitigate SEE. If using current share, tie PGOOD of the master to PGOOD of the slave.</p> |

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Pin Descriptions (Continued)

| R64.A PIN NUMBER | R64.C PIN NUMBER | PIN NAME | DESCRIPTION |
|--|---------------------|----------|---|
| 14 | | ISHCOM | ISHCOM is a bidirectional communication line between a current share master and a current share slave. If using current share, tie ISHCOM of the master to ISHCOM of the slave. The master enables the slave by resistively (~ 8.5kΩ) pulling ISHCOM high. The slave indicates an overcurrent fault condition to the master by pulling ISHCOM low. To mitigate SET, connect a 47pF ceramic capacitor from ISHCOM to the PCB ground plane. If not using current share this pin should be floated or connected to the PCB ground plane. ISHCOM is tri-stated if ISHEN is low. |
| 15 | | ISHSL | This pin is a logic input that is used to configure the IC as a current share master or slave. Tie this pin to DVDD to configure the IC as a current share slave. Tie this pin to the PCB ground plane to configure the IC as a current share master, or if the current share feature is not being used. |
| 16 | | ISHEN | This pin is an input that enables/disables the current share feature. To enable the current share feature, tie this pin to DVDD. To disable the current share feature, tie this pin to the PCB ground plane. |
| 17 | | PORSEL | This pin is the input for selecting the rising and falling POR (Power-On-Reset) thresholds. For a nominal 5V supply, connect this pin to DVDD. For a nominal 3.3V supply, connect this pin to DGND. For nominal supply voltages between 5V and 3.3V, connect this pin to DGND. |
| 18 | | TDO | This pin is the test data output of the internal BIT circuitry. Connect this pin to the PCB ground plane. |
| 19 | | TDI | This pin is the test data input of the internal BIT circuitry. Connect this pin to the PCB ground plane. |
| 20 | | TPGM | This pin is a trim input and is used to adjust various internal circuitry. Connect this pin to the PCB ground plane. |
| 21 | | GND | This pin is connected to an internal metal die trace that serves as a sensitive node noise shield. Connect this pin to the PCB ground plane. |
| 22 | | SYNC | When SYNC is configured as an output (clock Master Mode, M/S = DVDD), this pin drives the SYNC input of another ISL70002SEH with a square wave that is inverted (~180° out-of-phase) from the master clock driving the master PWM circuits. When configured as an input (clock Slave Mode, M/S = DGND), this pin uses the SYNC output from another ISL70002SEH or an external clock to drive the clock slave PWM circuitry. If synchronizing to an external clock, the clock must be SEE hardened and the frequency must be within the range of 400kHz to 1.2MHz. |
| 23, 28, 32, 37, 38, 43, 44, 49, 53, 58 | | PVINx | These pins are the power supply inputs to the corresponding internal power blocks. These pins must be connected to a common power supply rail, which must fall in the range of 3V to 5.5V. Bypass these pins directly to PGNDx with ceramic capacitors located as close as possible to the IC. PVINx should be the same voltage as DVDD and AVDD (±200mV). |
| 24, 27, 33, 36, 39, 42, 45, 48, 54, 57 | | LXx | These pins are the outputs of the corresponding internal power blocks and should be connected to the output filter inductor. Internally, these pins are connected to the synchronous MOSFET power switches. |
| 25, 26, 34, 35, 40, 41, 46, 47, 55, 56 | | PGNDx | These pins are the power grounds associated with the corresponding internal power blocks. These pins also provide the ground path for the metal package lid. Connect these pins directly to the PCB ground plane. These pins should also connect to the negative terminals of the input and output capacitors. Locate the input and output capacitors as close as possible to the IC. |
| 29 | | M/S | This pin is the clock master/slave input for selecting the direction of the bidirectional SYNC pin. For SYNC = Output (Master Mode), connect this pin to DVDD. For SYNC = Input (Slave Mode), connect this pin to the PCB ground plane. |
| 30 | | FSEL | This pin is the oscillator frequency select input. Tie this pin to DVDD to select a 1MHz nominal oscillator frequency. Tie this pin to the PCB ground plane to select a 500kHz nominal oscillator frequency. |
| 31, 50 | 31 | NC, HS | These are No Connect pins that are not connected to anything internally. They should be connected to the PCB ground plane. |
| N/A | 50 | HS | For the R64.C package (heatsink option) this pin is electrically connected to the heatsink on the underside of the package. Connect this pin and/or the heatsink to a thermal plane. |

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Pin Descriptions (Continued)

| R64.A PIN NUMBER | R64.C PIN NUMBER | PIN NAME | DESCRIPTION |
|---------------------|---------------------|-----------------|---|
| 51, 52 | | SC0/SC1 | <p>These pins are the inputs that comprise a 2-bit code to select the slope compensation (SC) current ramp referred to the output as shown below:</p> <p>SC1 = DVDD, SC0 = DVDD: SC = 6.6A/μs for FSEL = DGND SC1 = DVDD, SC0 = DGND: SC = 3.3A/μs for FSEL = DGND SC1 = DGND, SC0 = DVDD: SC = 1.6A/μs for FSEL = DGND SC1 = DGND, SC0 = DGND: SC = 0.8A/μs for FSEL = DGND</p> <p>SC1 = DVDD, SC0 = DVDD: SC = 13.4A/μs for FSEL = DVDD SC1 = DVDD, SC0 = DGND: SC = 6.7A/μs for FSEL = DVDD SC1 = DGND, SC0 = DVDD: SC = 3.4A/μs for FSEL = DVDD SC1 = DGND, SC0 = DGND: SC = 1.7A/μs for FSEL = DVDD</p> <p>If using current share, SC0 and SC1 of the slave MUST match the master SC0 and SC1.</p> |
| 59 | | EN | <p>This pin is the enable input to the IC. This is a comparator type input with a rising threshold of 0.6V and programmable hysteresis. Driving this pin above 0.6V enables the IC. Bypass this pin to the PCB ground plane with a 10nF ceramic capacitor to mitigate SEE.</p> |
| 60, 62 | | OCSSB/ OCSSA | <p>These pins are used to set the redundant A/B peak overcurrent limit threshold during soft-start. Connect a resistor from OCSSx to OCx in accordance with the following Equation: $ROCSSx (k\Omega) = (60 \times ROCx) / [(IOCSSx \times ROCx) - 60]$, where ROCx (kΩ) is the resistor value chosen to set the peak overcurrent limit during normal operation and IOCSSx (A) is the desired peak current limit threshold during soft-start.</p> |
| 61, 63 | | OCB/OCA | <p>These pins are used to set the redundant A/B peak overcurrent limit threshold during normal operation. Connect a resistor from this pin to the PCB ground plane in accordance with the following Equation: $ROCx (k\Omega) = 60 / IOC$, where IOC (A) is the desired peak current limit threshold during normal operation.</p> |
| 64 | | REF | <p>This pin is the internal reference voltage output. Bypass this pin to the PCB ground plane with a 220nF ceramic capacitor located as close as possible to the IC. The bypass capacitor is needed to mitigate SEE. No current (sourcing or sinking) is available from this pin. If using current share, tie REF of the master to REF of the slave through a 10Ω resistor.</p> |

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Typical Application Schematic (Continued)

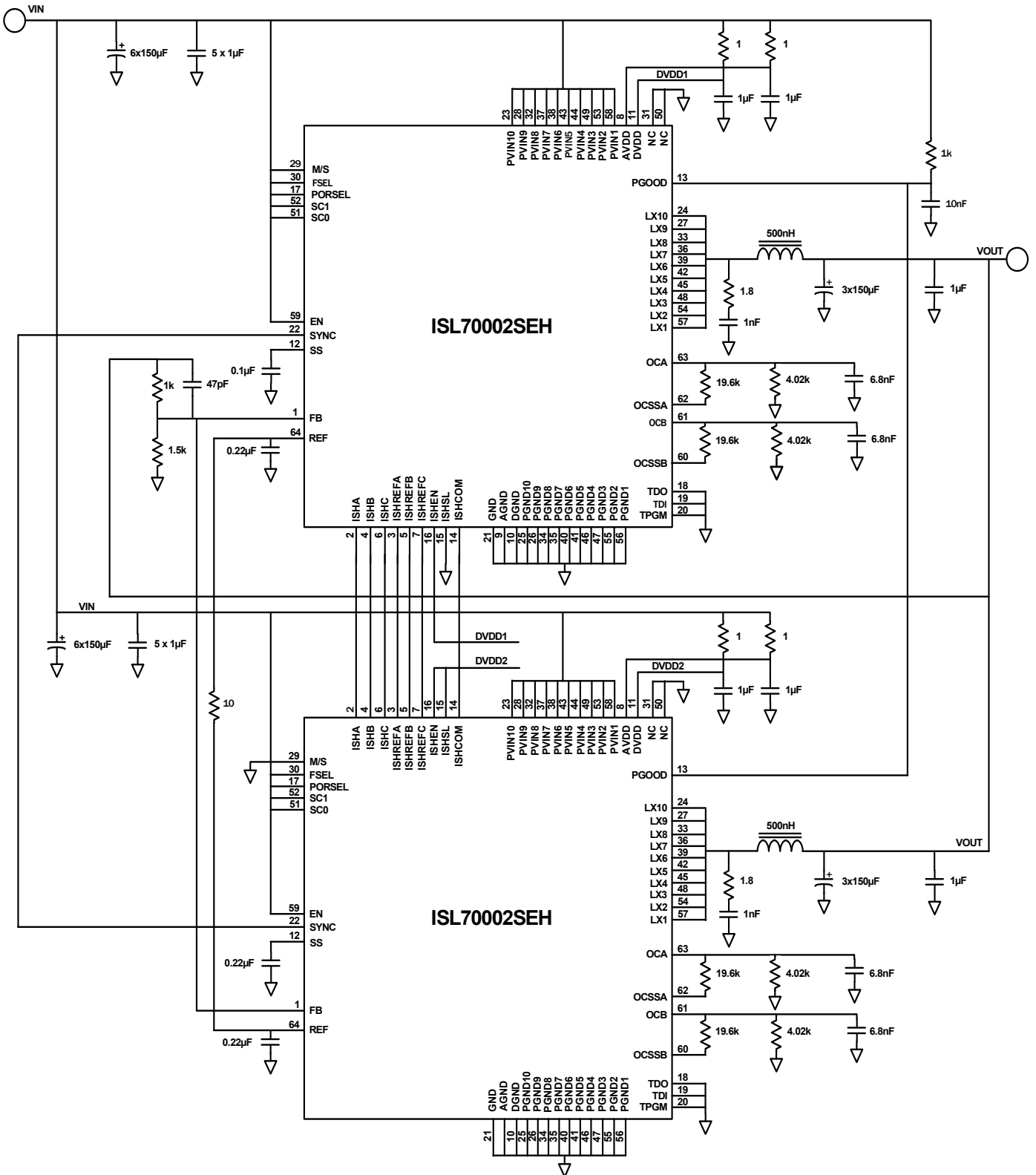


FIGURE 5. TWO-PHASE OPERATION WITH CURRENT SHARING

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Absolute Maximum Ratings in a Heavy Ion Environment [\(Note 4\)](#)

| | |
|--|------------------------------|
| AVDD | AGND - 0.3V to AGND + 6.2V |
| DVDD | DGND - 0.3V to DGND + 6.2V |
| LXx, PVINx (Note 11) | PGNDx - 0.3V to PGNDx + 6.2V |
| AVDD - AGND, DVDD - DGND | PVINx - PGNDx ± 0.3V |
| Signal Pins (Note 9) | AGND - 0.3V to AVDD + 0.3V |
| Digital Control Pins (Note 10) | DGND - 0.3V to DVDD + 0.3V |
| PGOOD | DGND - 0.3V to DGND + 6.2V |
| SS | DGND - 0.3V to DGND + 2.5V |

Absolute Maximum Ratings without Heavy Ions

| | |
|--|------------------------------|
| AVDD | AGND - 0.3V to AGND + 6.5V |
| DVDD | DGND - 0.3V to DGND + 6.5V |
| LXx, PVINx (Note 11) | PGNDx - 0.3V to PGNDx + 6.5V |
| AVDD - AGND, DVDD - DGND | PVINx - PGNDx ± 0.3V |
| Signal Pins (Note 9) | AGND - 0.3V to AVDD + 0.3V |
| Digital Control Pins (Note 10) | DGND - 0.3V to DVDD + 0.3V |
| PGOOD | DGND - 0.3V to DGND + 6.5V |
| SS | DGND - 0.3V to DGND + 2.5V |

Thermal Information

| | | |
|---|---------------------------|----------------------|
| Thermal Resistance | θ_{JA} (°C/W) | θ_{JC} (°C/W) |
| CQFP Package R64.A (Notes 5, 7) | 34 | 1.5 |
| CQFP Package R64.C (Notes 6, 8) | 17 | 0.7 |
| Operating Junction Temperature Range | -55°C to +150°C | |
| Storage Temperature Range | -65°C to +150°C | |
| Pb-Free Reflow Profile | see TB493 | |

Recommended Operating Conditions

| | |
|--|----------------------|
| AVDD | AGND + 3V to 5.5V |
| DVDD | DGND + 3V to 5.5V |
| PVINx | PGNDx + 3V to 5.5V |
| AVDD - AGND, DVDD - DGND | PVINx - PGNDx ± 0.1V |
| Signal pins (Note 9) | AGND to AVDD |
| Digital control pins (Note 10) | DGND to DVDD |
| REF, SS | Internally Set |
| GND, TDI, TDO, TPGM | DGND |
| I_{LXx} ($T_J \leq +150^\circ\text{C}$) | 0A to 1.2A |
| Ambient Temperature Range | -55°C to +125°C |

CAUTION: Do not operate at or near the maximum ratings listed for extended periods of time. Exposure to such conditions may adversely impact product reliability and result in failures not covered by warranty.

NOTES:

- Absolute Maximum Ratings assume operation in a heavy ion environment with $LET = 86.4 \text{ MeV} \cdot \text{cm}^2/\text{mg}$
- θ_{JA} is measured in free air with the component mounted on a high effective thermal conductivity test board. See Tech Brief [TB379](#) or details.
- θ_{JA} is measured in free air with the component mounted on a high effective thermal conductivity test board with “direct attach” features. See Tech Brief [TB379](#).
- For θ_{JC} , the “case temp” location is the center of the package underside.
- For θ_{JC} , the “case temp” location is the center of the exposed metal heatsink on the package underside.
- EN, FB, ISHx, ISHREFx, OCx, OCSSx, PORSEL and REF pins.
- FSEL, GND, ISHCOM, ISHEN, ISHRSL, M/S, SYNC, SCO, SC1, TDI, TDO and TPGM pins.
- The 6.2V absolute maximum rating must be met for a 20MHz bandwidth limited observation at the device pins. In addition, for a 600MHz bandwidth limited observation, the peak transient voltage on PVINx (measured to PGNDx) must be less than 7.1V with a duration above 6.2 V of less than 10ns, and the peak transient voltage on LXx (measured to PGNDx) must be less than 7.9V with a duration above 6.2 V of less than 10ns.

Electrical Specifications Unless otherwise noted, $V_{IN} = AVDD = DVDD = PVINx = EN = FSEL = M/S = SCO = SC1 = 3V$ to 5.5V; $GND = AGND = DGND = PGNDx = ISHx = ISHCOM = ISHEN = ISHREFx = ISHSL = TDI = TDO = TPGM = 0V$; $FB = 0.65V$; $PORSEL = V_{IN}$ for $4.5V \leq V_{IN} \leq 5.5V$ and GND for $V_{IN} < 4.5V$; $LXx = SYNC = \text{Open Circuit}$; OCx is connected to $OCSSx$ with a $10k\Omega$ resistor; OCx is connected to GND with a $4.99k\Omega$ resistor shunted by a $6.8nF$ capacitor; $PGOOD$ is pulled up to V_{IN} with a $1k\Omega$ resistor; REF is bypassed to GND with a $220nF$ capacitor; SS is bypassed to GND with a $100nF$ capacitor; $T_A = T_J = -55^\circ\text{C}$ to $+125^\circ\text{C}$; Post 100krad(Si). [\(Note 9\)](#).

| PARAMETER | TEST CONDITIONS | MIN (Note 13) | TYP (Note 12) | MAX (Note 13) | UNITS |
|--|--|----------------------------------|----------------------------------|----------------------------------|-------|
| POWER SUPPLY | | | | | |
| Operating Supply Current (Current Share Disabled) | $V_{IN} = 5.5V$ | | 70 | 105 | mA |
| | $V_{IN} = 3.6V$ | | 43 | 65 | mA |
| Standby Supply Current (Current Share Disabled) | $V_{IN} = 5.5V$, $EN = GND$, $ISHEN = GND$ | | 2.5 | 6 | mA |
| | $V_{IN} = 3.6V$, $EN = GND$, $ISHEN = GND$ | | 2 | 4 | mA |
| Operating Supply Current (Current Share Enabled, Current Share Master) | $V_{IN} = ISHEN = 5.5V$, $ISHCOM = \text{Open Circuit}$ | | 70 | 120 | mA |
| Operating Supply Current (Current Share Enabled, Current Share Slave) | $V_{IN} = ISHEN = ISHSL = 5.5V$, $ISHCOM$ pulled to V_{IN} with $1k\Omega$, $M/S = GND$, $ISHx = ISHREFx = -100\mu\text{A}$, $SYNC = \text{external } 1\text{MHz clock}$ | | 70 | 120 | mA |

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Electrical Specifications Unless otherwise noted, $V_{IN} = AVDD = DVDD = PVINx = EN = FSEL = M/S = SC0 = SC1 = 3V$ to 5.5V; $GND = AGND = DGND = PGNDx = ISHx = ISHCOM = ISHEN = ISHREFx = ISHSL = TDI = TDO = TPGM = 0V$; $FB = 0.65V$; $PORSEL = V_{IN}$ for $4.5V \leq V_{IN} \leq 5.5V$ and GND for $V_{IN} < 4.5V$; $LXx = SYNC = \text{Open Circuit}$; OCx is connected to $OCSSx$ with a $10k\Omega$ resistor; OCx is connected to GND with a $4.99k\Omega$ resistor shunted by a $6.8nF$ capacitor; $PGOOD$ is pulled up to V_{IN} with a $1k\Omega$ resistor; REF is bypassed to GND with a $220nF$ capacitor; SS is bypassed to GND with a $100nF$ capacitor; $T_A = T_J = -55^\circ C$ to $+125^\circ C$; Post 100krad(Si). (Note 9). (Continued)

| PARAMETER | TEST CONDITIONS | MIN (Note 13) | TYP (Note 12) | MAX (Note 13) | UNITS |
|--|--|------------------|------------------|------------------|-----------|
| Standby Supply Current (Current Share Enabled, Current Share Slave) | $V_{IN} = ISHEN = ISHSL = 5.5V$, $EN = M/S = GND$, $SYNC = \text{external } 1MHz \text{ clock}$ | | 3.0 | 7 | mA |
| | $V_{IN} = ISHEN = ISHSL = 5.5V$, $M/S = GND$, $SYNC = \text{external } 1MHz \text{ clock}$, $ISHCOM = GND$ | | 7.3 | 11 | mA |
| OUTPUT VOLTAGE AND CURRENT | | | | | |
| Reference Voltage | | 0.594 | 0.6 | 0.606 | V |
| Output Voltage Tolerance | $V_{OUT} = 0.8V$ to $2.5V$, $I_{OUT} = 0A$ to $12A$ (Notes 14, 15) | -2 | | 2 | % |
| Error Amp Input Offset Voltage | $V_{IN} = 5.5V$, $V_{REF} = 600mV$, test mode | -1 | | 3 | mV |
| Feedback (FB) Input Leakage Current | $V_{IN} = 5.5V$, $V_{FB} = 600mV$ | -1.5 | | 1.5 | μA |
| Sustained Output Current | $V_{IN} = 3V$, $V_{OUT} = 1.8V$, $OCA = OCB = PVIN$ (Note 16) | 16 | 22 | | A |
| PWM CONTROL LOGIC | | | | | |
| Internal Oscillator Tolerance | $FSEL = V_{IN}$ or GND | -15 | | 15 | % |
| External Oscillator Range | $M/S = GND$ | 0.4 | | 1.2 | MHz |
| Minimum LXx On-Time | $V_{IN} = 5.5V$, test mode | | 200 | 275 | ns |
| Minimum LXx Off-Time | $V_{IN} = 5.5V$, test mode | | 0 | 50 | ns |
| Minimum LXx On-Time | $V_{IN} = 3V$, test mode | | 225 | 300 | ns |
| Minimum LXx Off-Time | $V_{IN} = 3V$, test mode | | 0 | 50 | ns |
| PORSEL, Master/Slave (M/S), SC1, SC0, ISHSL, ISHEN, FSEL Input Voltage | Input high threshold | $V_{IN} - 0.5$ | 1.3 | | V |
| | Input low threshold | | 1.2 | 0.5 | V |
| PORSEL, Master/Slave (M/S), SC1, SC0, ISHSL, ISHEN, FSEL Input Leakage Current | $V_{IN} = 5.5V$ | -1 | | 1 | μA |
| Synchronization (SYNC) Input Voltage | Input high threshold, $M/S = GND$ | 2.3 | 1.7 | | V |
| | Input Low Threshold, $M/S = GND$ | | 1.5 | 1 | V |
| Synchronization (SYNC) Input Leakage Current | $V_{IN} = 5.5V$, $M/S = GND$, $SYNC = V_{IN}$ or GND | -1 | | 1 | μA |
| Synchronization (SYNC) Output Voltage | $V_{IN} - V_{OH}$ at $I_{OH} = -1mA$ | | 0.1 | 0.4 | V |
| | V_{OL} at $I_{OL} = 1mA$ | | 0.1 | 0.4 | V |
| POWER BLOCKS | | | | | |
| Upper Device $r_{DS(ON)}$ | $V_{IN} = 3V$, 4A load, all power blocks in parallel, test mode (Note 12) | | 20 | 40 | $m\Omega$ |
| Lower Device $r_{DS(ON)}$ | $V_{IN} = 3V$, 4A load, all power blocks in parallel, test mode (Note 12) | | 15 | 30 | $m\Omega$ |
| LXx Output Leakage | $V_{IN} = 5.5V$, $EN = LXx = GND$, single LXx output | -1 | | | μA |
| | $V_{IN} = LXx = 5.5V$, $EN = GND$, single LXx output | | | 10 | μA |
| Dead Time (Note 15) | Within a single power block or between power blocks | 2.2 | 25 | | ns |
| Efficiency (Note 15) | $V_{IN} = 3.3V$, $V_{OUT} = 1.8V$, $I_{OUT} = 6A$, $FSEL = GND$ | | 88 | | % |
| | $V_{IN} = 5V$, $V_{OUT} = 2.5V$, $I_{OUT} = 6A$ | | 90 | | % |

ISL70002SEH

Electrical Specifications Unless otherwise noted, $V_{IN} = AVDD = DVDD = PVINx = EN = FSEL = M/S = SC0 = SC1 = 3V$ to 5.5V; $GND = AGND = DGND = PGNDx = ISHx = ISHCOM = ISHEN = ISHREFx = ISHSL = TDI = TDO = TPGM = 0V$; $FB = 0.65V$; $PORSEL = V_{IN}$ for 4.5V $\leq V_{IN} \leq 5.5V$ and GND for $V_{IN} < 4.5V$; $LXx = SYNC = \text{Open Circuit}$; OCx is connected to $OCSSx$ with a 10k Ω resistor; OCx is connected to GND with a 4.99k Ω resistor shunted by a 6.8nF capacitor; $PGOOD$ is pulled up to V_{IN} with a 1k Ω resistor; REF is bypassed to GND with a 220nF capacitor; SS is bypassed to GND with a 100nF capacitor; $T_A = T_J = -55^\circ C$ to $+125^\circ C$; Post 100krad(Si). (Note 9). (Continued)

| PARAMETER | TEST CONDITIONS | MIN (Note 13) | TYP (Note 12) | MAX (Note 13) | UNITS |
|------------------------------------|--|------------------|------------------|------------------|--------------|
| POWER-ON RESET | | | | | |
| VIN POR | Rising threshold, PORSEL = V_{IN} | 4.1 | 4.3 | 4.45 | V |
| | Hysteresis, PORSEL = V_{IN} | 225 | 325 | 425 | mV |
| | Rising threshold, PORSEL = GND | 2.65 | 2.8 | 2.95 | V |
| | Hysteresis, PORSEL = GND | 70 | 140 | 240 | mV |
| Enable (EN) Input Voltage | Rising/falling threshold | 0.56 | 0.6 | 0.64 | V |
| Enable (EN) Input Leakage Current | $V_{IN} = 5.5V$, EN = V_{IN} or GND | -3 | | 3 | μA |
| Enable (EN) Sink Current | EN = 0.3V | 6.4 | 11 | 16.6 | μA |
| SOFT-START | | | | | |
| Soft-Start Source Current | SS = GND | 20 | 23 | 27 | μA |
| Soft-Start Discharge ON-Resistance | | | 2.2 | 4.7 | Ω |
| Soft-Start Discharge Time | | | 256 | | Clock Cycles |
| POWER-GOOD SIGNAL | | | | | |
| Rising Threshold | V_{FB} as a % of V_{REF} , test mode | 107 | 111 | 115 | % |
| Rising Hysteresis | V_{FB} as a % of V_{REF} , test mode | 2 | 3.5 | 5 | % |
| Falling Threshold | V_{FB} as a % of V_{REF} , test mode | 85 | 89 | 93 | % |
| Falling Hysteresis | V_{FB} as a % of V_{REF} , test mode | 2 | 3.5 | 5 | % |
| Power-Good Drive | $V_{IN} = 3V$, PGOOD = 0.4V, EN = GND | 7.2 | | | mA |
| Power-Good Leakage | $V_{IN} = PGOOD = 5.5V$ | | | 1 | μA |
| PROTECTION FEATURES | | | | | |
| Undervoltage Monitor | | | | | |
| Undervoltage Trip Threshold | V_{FB} as a % of V_{REF} , test mode | 71 | 75 | 79 | % |
| Undervoltage Recovery Threshold | V_{FB} as a % of V_{REF} , test mode | 84 | 88 | 92 | % |
| Overcurrent Monitor | | | | | |
| Overcurrent Trip Level | $I_{OCx} = 60\mu A$, test mode (Note 17) | 5.35 | | 7.35 | A |
| | $I_{OCx} = 240\mu A$, test mode (Note 17) | 23 | | 26 | A |
| CURRENT SHARE | | | | | |
| Slave Load Current | Master load current = 12A, $V_{IN} = 3.3V$, $V_{OUT} = 0.8V$, SC1 = ISHSL = M/S = 0, SC0 = ISHEN = FSEL = 1, SYNC = 1MHz external, 500nH inductor (Notes 15, 16) | 7 | 12 | 17 | A |
| | Master load current = 12A, $V_{IN} = 3.3V$, $V_{OUT} = 1.8V$, SC0 = ISHSL = M/S = 0, SC1 = ISHEN = FSEL = 1, SYNC = 1MHz external, 500nH inductor (Notes 15, 16) | 7 | 12 | 17 | A |
| | Master load current = 12A, $V_{IN} = 5.0V$, $V_{OUT} = 1.8V$, SC0 = ISHSL = M/S = 0, SC1 = ISHEN = FSEL = 1, SYNC = 1MHz external, 500nH inductor (Notes 15, 16) | 7 | 12 | 17 | A |
| | Master load current = 12A, $V_{IN} = 5.0V$, $V_{OUT} = 2.5V$, ISHSL = M/S = 0, SC0 = SC1 = ISHEN = FSEL = 1, SYNC = 1MHz external, 500nH inductor (Notes 15, 16) | 7 | 12 | 17 | A |

ISL70002SEH

Electrical Specifications Unless otherwise noted, $V_{IN} = AVDD = DVDD = PVINx = EN = FSEL = M/S = SC0 = SC1 = 3V$ to 5.5V; $GND = AGND = DGND = PGNDx = ISHx = ISHCOM = ISHEN = ISHREFx = ISHSL = TDI = TDO = TPGM = 0V$; $FB = 0.65V$; $PORSEL = V_{IN}$ for $4.5V \leq V_{IN} \leq 5.5V$ and GND for $V_{IN} < 4.5V$; $LXx = SYNC = \text{Open Circuit}$; OCx is connected to $OCCSSx$ with a $10k\Omega$ resistor; OCx is connected to GND with a $4.99k\Omega$ resistor shunted by a $6.8nF$ capacitor; $PGOOD$ is pulled up to V_{IN} with a $1k\Omega$ resistor; REF is bypassed to GND with a $220nF$ capacitor; SS is bypassed to GND with a $100nF$ capacitor; $T_A = T_J = -55^\circ C$ to $+125^\circ C$; Post 100krad(Si). (Note 9). (Continued)

| PARAMETER | TEST CONDITIONS | MIN (Note 13) | TYP (Note 12) | MAX (Note 13) | UNITS |
|--|--|------------------|------------------|------------------|---------------|
| ISHx, ISHREFx, Tri-State Leakage Current | $V_{IN} = 5.5V, EN = GND$ | -1 | 0 | 1 | μA |
| Master ISHCOM Pull-Up Resistance | $ISHCOM = -50\mu A$ | 6.5 | 10 | 13 | $k\Omega$ |
| Slave ISHCOM Input Leakage Current | $V_{IN} = ISHSL = 5.5V$ | -1 | | 1 | μA |
| Slave ISHCOM Pull-Down Resistance | $ISHSL = V_{IN}, EN = GND, ISHCOM = 7.2mA$ | 35 | 75 | 125 | Ω |
| Slave ISHCOM Input High Voltage | $ISHSL = V_{IN}$ | 42 | 52 | 62 | % of V_{IN} |
| Slave ISHCOM Input Low Voltage | $ISHSL = V_{IN}$ | 26 | 36 | 46 | % of V_{IN} |
| Slave ISHCOM Input Voltage Hysteresis | $ISHSL = V_{IN}$ | 7 | 16 | 24 | % of V_{IN} |
| ISHSL Input Leakage Current | | -1 | | 1 | μA |
| ISHSL Input High Voltage | | $V_{IN} - 0.5$ | 1.3 | | V |
| ISHSL Input Low Voltage | | | 1.2 | 0.5 | V |
| SLOPE COMPENSATION | | | | | |
| | $SC1 = SC0 = V_{IN}$ | 5.9 | 13.4 | 17.7 | $A/\mu s$ |
| | $SC1 = V_{IN}, SC0 = GND$ | 3.0 | 6.7 | 8.8 | $A/\mu s$ |
| | $SC1 = GND, SC0 = V_{IN}$ | 1.5 | 3.4 | 4.5 | $A/\mu s$ |
| | $SC1 = SC0 = GND$ | 0.7 | 1.7 | 2.2 | $A/\mu s$ |
| | $FSEL = GND, SC1 = SC0 = V_{IN}$ | 2.9 | 6.6 | 8.8 | $A/\mu s$ |
| | $FSEL = GND, SC1 = V_{IN}, SC0 = GND$ | 1.4 | 3.3 | 4.5 | $A/\mu s$ |
| | $FSEL = GND, SC1 = GND, SC0 = V_{IN}$ | 0.7 | 1.6 | 2.2 | $A/\mu s$ |
| | $FSEL = GND, SC1 = SC0 = GND$ | 0.3 | 0.8 | 1.2 | $A/\mu s$ |

NOTES:

12. Typical values shown reflect $T_A = T_J = +25^\circ C$ operation and are not guaranteed.
13. Parameters with MIN and/or MAX limits are 100% tested at $-55^\circ C, +25^\circ C$ and $+125^\circ C$, unless otherwise specified.
14. Limits do not include tolerance of external feedback resistors. The 0A to 12A output current range may be reduced by Minimum LXx On-time and Minimum LXx Off-time specifications.
15. Limits established by characterization or analysis and are not production tested.
16. Tested sequentially on LX2, LX6 and LX9.
17. Tested sequentially on LX2 and LX6 at 535mA to 735mA and 2.3A to 2.6A.
18. Tested in accordance with MIL-STD-883, method 1019, condition A.

Typical Performance Curves

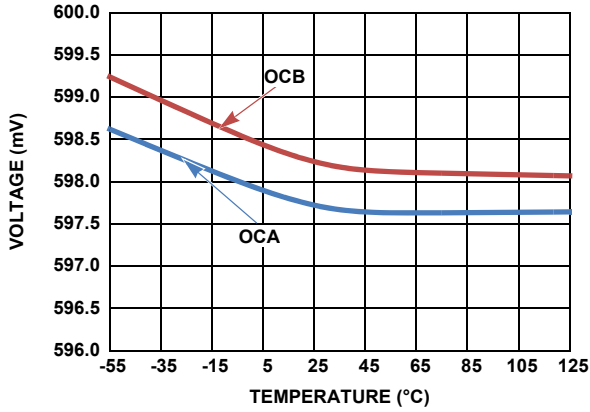


FIGURE 6. OVERCURRENT REFERENCE VOLTAGE

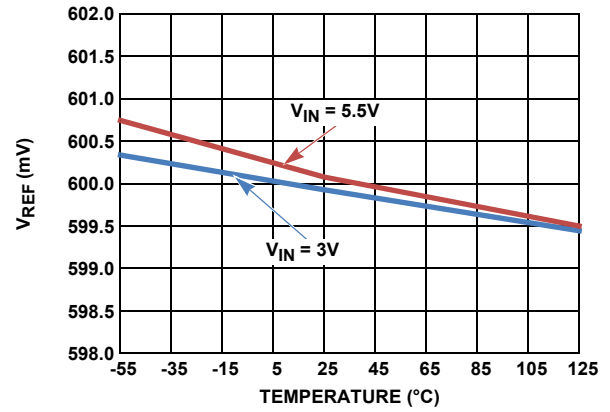


FIGURE 7. REF VOLTAGE vs V_{IN}

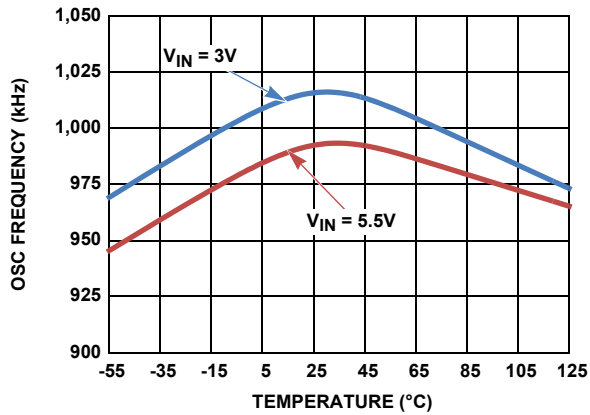


FIGURE 8. OSC FREQUENCY vs V_{IN}

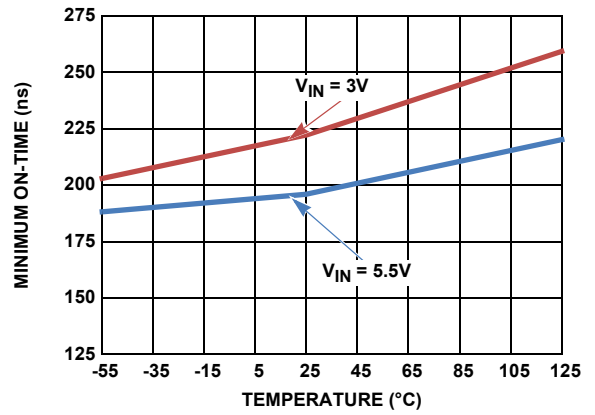


FIGURE 9. LXx MINIMUM ON-TIME vs V_{IN}

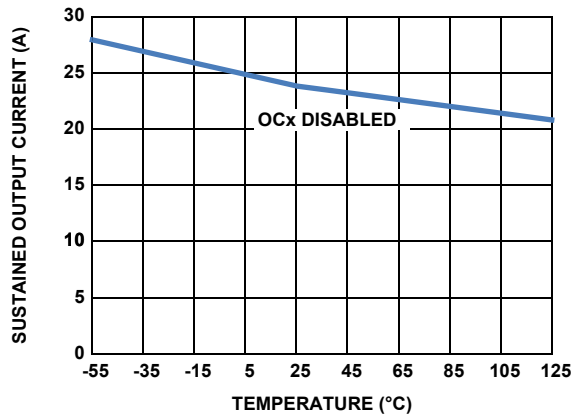


FIGURE 10. SUSTAINED OUTPUT CURRENT WITH OVERCURRENT DISABLED

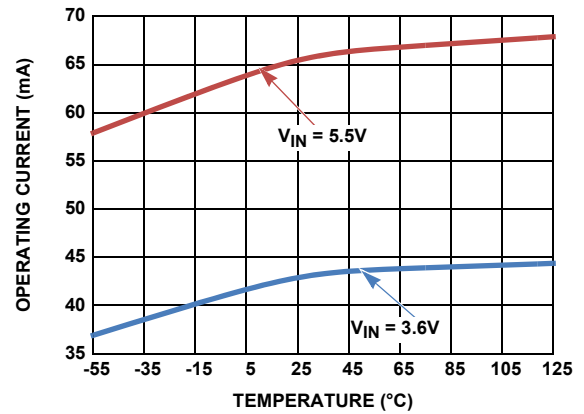


FIGURE 11. OPERATING CURRENT vs V_{IN}

Typical Performance Curves (Continued)

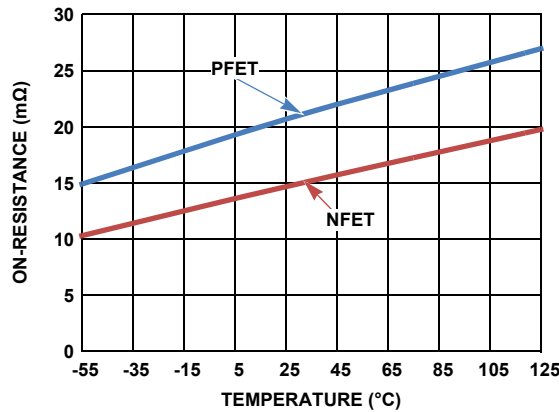
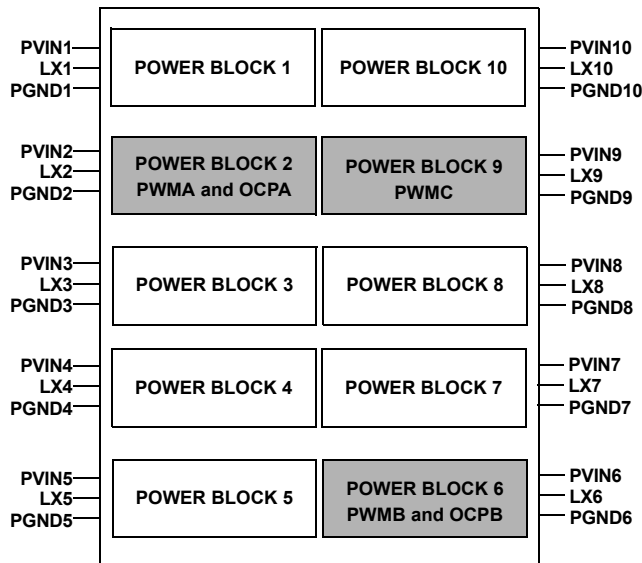


FIGURE 12. LX ON-RESISTANCE, ALL POWER BLOCKS IN PARALLEL, $V_{IN} = 3V$

Functional Description

The ISL70002SEH is a monolithic, fixed frequency, current-mode synchronous buck regulator. Two ISL70002SEH devices can be used to provide a total DC/DC solution for FPGAs, CPLDs, DSPs and CPUs.



Note: Shaded blocks indicate pilot current and overcurrent sensors.

FIGURE 13. POWER BLOCK DIAGRAM

Power Blocks

The power output stage of the regulator consists of ten power blocks that are paralleled to provide full 12A output current capability. The block diagram in Figure 13 shows a top level view of the individual power blocks.

Each power block has a power supply input pin, $PVIN_x$, a phase output pin, LX_x and a power supply ground pin, $PGND_x$. All $PVIN_x$ pins must be connected to a common power supply rail and all $PGND_x$ pins must be connected to a common ground. LX_x pins should be connected to the output inductor based on the required load current, but must include the LX_2 , LX_6 and LX_9 pins. For example, if 6A of output current is needed, any five LX_x pins can be connected to the inductor as long as three of them are the LX_2 , LX_6 and LX_9 pins. The unused LX_x pins should be left unconnected. Connecting all ten LX_x pins to the output inductor provides a maximum 12A of output current at +150°C die temperature. See the "Typical Application Schematic" on page 7 for pin connection guidance.

Power block 2, 6 and 9 contains the master pilot devices, which provide current feedback and this is why they must be connected to the output inductor.

Main Control Loop

During normal operation, the internal top power switch is turned on at the beginning of each clock cycle. Current in the output inductor ramps up until the current comparator trips and turns off the top power MOSFET. Then the bottom power MOSFET turns on and the inductor current ramps down for the rest of the cycle.

The current comparator compares the output current at the ripple current peak to the scaled current pilot. The error amplifier monitors V_{OUT} and compares it with an internal reference voltage. The output voltage of the error amplifier creates a proportional current to the pilot. If V_{OUT} is low, the current level of the pilot is increased and the trip off current level of the output is increased. The increased output current raises V_{OUT} until it is in agreement with the reference voltage.

Output Voltage Selection

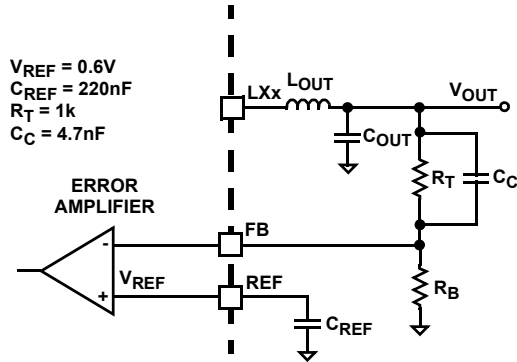


FIGURE 14. OUTPUT VOLTAGE SELECTION

The output voltage of the ISL70002SEH can be adjusted using an external resistor divider as shown in [Figure 14](#). R_T should be selected as 1k Ω to mitigate SEE. R_T should be shunted by a 4.7nF ceramic capacitor, C_C , to mitigate SEE and to improve loop stability margins. The REF pin should be bypassed to AGND with a 220nF ceramic capacitor to mitigate SEE. It should be noted that no current (sourcing or sinking) is available from the REF pin. R_B can be determined from [Equation 3](#). The designer can configure the output voltage from 0.8V to 85% of the input voltage.

$$R_B = R_T \cdot \frac{V_{REF}}{V_{OUT} - V_{REF}} \quad (\text{EQ. 3})$$

The minimum on-time determines the lowest output voltage, so when $V_{IN} = 5.5\text{V}$ and the switching frequency is 500kHz this parameter limits the regulated output voltage to about 0.8V or greater. It increases at the 1MHz switching frequency to about 1.6V or greater. The minimum on-time increases by about 9% at $V_{IN} = 3\text{V}$, but the 500kHz output voltage is not limited by the minimum on-time and the 1MHz minimum V_{OUT} is approximately 0.9V.

Switching Frequency/Synchronization

The ISL70002SEH features an internal oscillator running at a fixed frequency of either 500kHz or 1MHz $\pm 15\%$ over recommended operating conditions. When the FSEL pin is grounded, the oscillator operated at 500kHz, and if FSEL is connected to DVDD it operates at 1MHz.

The regulator can be configured to run from the internal oscillator or can be synchronized to another ISL70002SEH or an SEE hardened external clock with a frequency range of 500kHz to 1MHz ($\pm 20\%$).

To run the regulator from the internal oscillator, connect the M/S pin to DVDD. In this case, the output of the internal oscillator appears on the SYNC pin. To synchronize two regulators to the SYNC output of an SEE hardened external clock, (or to another ISL70002SEH regulator, see [“Synchronized 2-Phase Operation”](#)) connect the M/S pin to DGND. In this case, the SYNC pin is an input that accepts an external synchronizing signal. When M/S is connected to DGND, the ISL70002SEH is synchronized 180° out-of-phase with respect to the SYNC input of the external clock. Operating two or more regulators with individual SYNC inputs ideally should be operated out-of-phase and balanced to reduce input current ripple and increase the effective switching frequency.

Synchronized 2-Phase Operation

The ISL70002SEH is capable of operating 2 ICs as a single 2-phase regulator with nearly twice the load current capacity. In this mode, a redundant current sharing bus balances the load current between the two devices and communicates any fault conditions. One ISL70002SEH is designated the master and the other the slave. The master ISHSL pin is connected to DGND and the slave ISHSL pin is connected to DVDD. The ISHEN pins on both master and slave are connected to DVDD. The SYNC, ISHA, ISHB, ISHC, ISHREFA, ISHREFB, ISHREFC, ISHCOM and FB pins are connected from the master to the slave and the REF pins are tied with a 10 Ω resistor. Configured this way, the two-phase regulator nearly doubles the load current capacity, limited only by the current share match tolerance.

In this master/slave configuration the ISL70002SEH ICs operate 180° out-of-phase to minimize the input ripple current, effectively operating as a single IC at twice the switching frequency. The master phase uses the falling edge of the SYNC clock to initiate the master switching cycle with the nonoverlap period before the rising edge of LX, while the slave phase internally inverts the SYNC input and uses the falling edge of the inverted copy to start its switching cycle. This is independent of whether the master phase is configured for an external clock (master M/S = DGND) or its internal clock (master M/S = DVDD). The master error amplifier and compensation controls the two-phase regulator while the slave error amplifier is disabled. The schematic in [Figure 5](#) shows the complete connections for the master and slave.

Operation Initialization

The ISL70002SEH initializes based on the state of the power-on reset (POR) monitor of the PVINx inputs and the state of the EN input. Successful initialization prompts a soft-start interval and the regulator begins slowly ramping the output voltage. Once the commanded output voltage is within the proper window of operation, the power-good signal changes state from low-to-high indicating proper regulator operation.

Power-On Reset

The POR circuitry prevents the controller from attempting to soft-start before sufficient bias is present at the PVINx pins.

The POR threshold of the PVINx pins is controlled by the PORSEL pin. For a nominal 5V supply voltage, PORSEL should be connected to the DVDD. For a nominal 3.3V supply voltage, PORSEL should be connected to DGND. For nominal supply voltages between 5V and 3.3V, PORSEL should be connected to DGND. The POR rising and falling thresholds are shown in the “Electrical Specifications” table on [page 11](#).

Hysteresis between the rising and falling thresholds ensures that small perturbations on PVINx seen during turn-on/turn-off of the regulator do not cause inadvertent turn-off/turn-on of the regulator. When the PVINx pins are below the POR rising threshold, the internal synchronous power MOSFET switches are turned off, and the LXx pins are held in a high-impedance state.

Enable and Disable

After the POR input requirement is met, the ISL70002SEH remains in shutdown until the voltage at the enable input rises above the enable threshold. Figure 15 shows that the enable circuit features a comparator type input. In addition to simple logic on/off control, the enable circuit allows the level of an external voltage to precisely gate the turn-on/turn-off of the regulator. An internal I_{EN} current sink with a typical value of $11\mu\text{A}$ is only active when the voltage on the EN pin is below the enable threshold. The current sink pulls the EN pin low. As $V_{CONTROL}$ rises, the enable level is not set exclusively by the resistor divider from $V_{CONTROL}$. With the current sink active, the enable level is defined by Equation 4. R_1 is the resistor from the EN pin to $V_{CONTROL}$ and R_2 is the resistor from the EN pin to the AGND pin.

$$V_{ENABLE} = V_{REF} \cdot \left[1 + \frac{R_1}{R_2} \right] + I_{EN} \cdot R_1 \quad (\text{EQ. 4})$$

Once the voltage at the EN pin reaches the enable threshold, the I_{EN} current sink turns off.

With the part enabled and the I_{EN} current sink off, the disable level is set by the resistor divider. The disable level is defined by Equation 5.

$$V_{DISABLE} = V_{REF} \cdot \left[1 + \frac{R_1}{R_2} \right] \quad (\text{EQ. 5})$$

The difference between the enable and disable levels provides adjustable hysteresis so that noise on $V_{CONTROL}$ does not interfere with the enabling or disabling of the regulator.

The EN pin should be bypassed to the AGND pin with a 10nF ceramic capacitor to mitigate SEE.

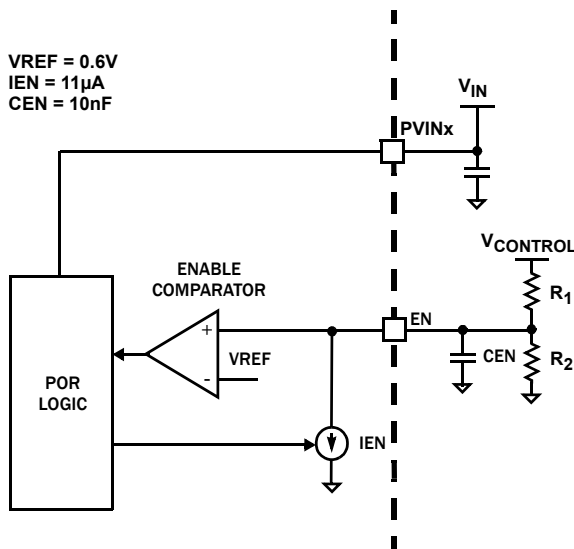


FIGURE 15. ENABLE CIRCUIT

Soft-Start

Once the POR and enable circuits are satisfied, the regulator initiates a soft-start. Figure 16 shows that the soft-start circuit clamps the error amplifier reference voltage to the voltage on an external soft-start capacitor connected to the SS pin. The soft-start capacitor is charged by an internal I_{SS} current source ($23\mu\text{A}$ typical). As the soft-start capacitor is charged, the output voltage slowly ramps to the set point determined by the reference voltage and the feedback network. Once the voltage on the SS pin is equal to the internal reference voltage (600mV), the soft-start interval is complete though the SS pin voltage continues to rise to approximately 1.4V . PGOOD is ENABLED after SS reached to 1.4V . The controlled ramp of the output voltage reduces the inrush current during start-up. The soft-start output ramp interval is defined in Equation 6 and is adjustable from approximately 2ms to 200ms . The value of the soft-start capacitor, C_{SS} , should range from 82nF to $8.2\mu\text{F}$, inclusive. The peak inrush current can be computed from Equation 7. The soft-start interval should be selected long enough to insure that the peak inrush current plus the peak output load current does not exceed the SS overcurrent trip level of the regulator.

$$t_{SS} = C_{SS} \cdot \frac{V_{REF}}{I_{SS}} \quad (\text{EQ. 6})$$

$$I_{INRUSH} = C_{OUT} \cdot \frac{V_{OUT}}{t_{SS}} \quad (\text{EQ. 7})$$

The soft-start capacitor is immediately discharged by a 2.2Ω resistor whenever POR conditions are not met or EN is pulled low. The soft-start discharge time is equal to 256 clock cycles.

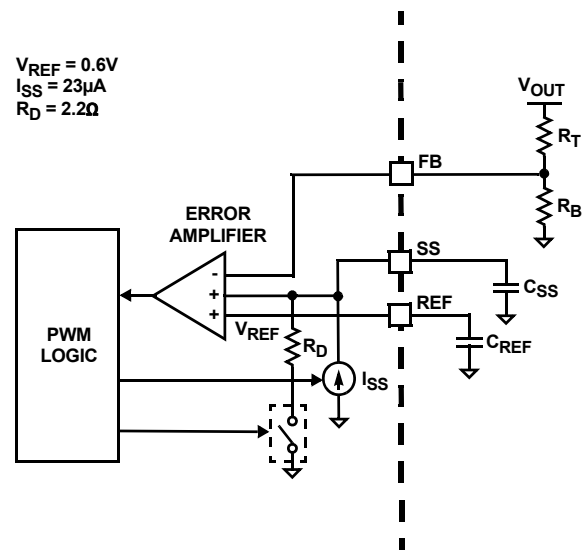


FIGURE 16. SOFT-START CIRCUIT

Power-Good

The power-good (PGOOD) pin is an open-drain logic output that indicates when the output voltage of the regulator is within regulation limits. The power-good pin pulls low during shutdown and remains low when the controller is enabled. After a successful soft-start, the PGOOD pin releases and the voltage rises with an external pull-up resistor. The power-good signal transitions low immediately when the EN pin is pulled low.

The power-good circuitry monitors the FB pin and compares it to the rising and falling thresholds shown in the “Electrical Specifications” table on [page 11](#). If the feedback voltage exceeds the typical rising limit of 111% of the reference voltage, the PGOOD pin pulls low. The PGOOD pin continues to pull low until the feedback voltage falls to a typical of 107.5% of the reference voltage. If the feedback voltage drops below a typical of 89% of the reference voltage, the PGOOD pin pulls low. The PGOOD pin continues to pull low until the feedback voltage rises to a typical 92.5% of the reference voltage. The PGOOD pin then releases and signals the return of the output voltage within the power-good window.

The PGOOD pin can be pulled up to any voltage from 0V to 5.5V, independent of the supply voltage. The pull-up resistor should have a nominal value from 1kΩ to 10kΩ. The PGOOD pin should be bypassed to DGND with a 10nF ceramic capacitor to mitigate SEE.

Slope Compensation

The SC0 and SC1 pins select four levels of current mode slope compensation. In current mode buck regulators, when the duty cycle approaches and exceeds 50%, the regulator will operate in sub-harmonic oscillation without slope compensation. Slope compensation is widely considered unnecessary if the duty cycle is held below 40% and provides better phase margin. Transient duty cycles must be taken into consideration when selecting the level of slope compensation. [Table 1](#) describes the amount of effective current that is added the output power stage signal that is used in the PWM modulator.

TABLE 1.

| FSEL | SC1 | SC0 | SLOPE COMPENSATION (A/μs) |
|------|------|------|---------------------------|
| DGND | DGND | DGND | 0.8 |
| DGND | DGND | DVDD | 1.6 |
| DGND | DVDD | DGND | 3.3 |
| DGND | DVDD | DVDD | 6.6 |
| DVDD | DGND | DGND | 1.7 |
| DVDD | DGND | DVDD | 3.4 |
| DVDD | DVDD | DGND | 6.7 |
| DVDD | DVDD | DVDD | 13.4 |

Fault Monitoring and Protection

The ISL70002SEH actively monitors output voltage and current to detect fault conditions. Fault conditions trigger protective measures to prevent damage to the regulator and external load device.

Undervoltage Protection

A hysteretic comparator monitors the FB pin of the regulator. The feedback voltage is compared to an undervoltage threshold that is a fixed percentage of the reference voltage. Once the comparator trips on two consecutive switching cycles, indicating a valid undervoltage condition, the undervoltage protection logic shuts down the regulator. If the feedback voltage rises back above the undervoltage threshold plus a specified amount of hysteresis (outlined in the “Electrical Specifications” table on [page 11](#)) after the first detection and before the second, normal operation continues.

After the regulator shuts down, it enters a delay interval, equivalent to the selected soft-start interval. The undervoltage counter is reset entering the delay interval. The protection logic initiates a normal soft-start once the delay interval ends. If the output successfully soft-starts, the power-good signal goes high and normal operation continues. If undervoltage conditions continue to exist during the soft-start interval, the undervoltage counter must overflow before the regulator shuts down again. This hiccup mode continues indefinitely until the output soft-starts successfully.

Overcurrent Protection

Pilot devices integrated into the PMOS transistor of Power Blocks 2 and 6 samples the inductor current of each cycle. This current feedback is scaled and compared to an overcurrent threshold based on the overcurrent resistor connected from OCx to AGND.

If the sampled current exceeds the overcurrent threshold, an overcurrent counter increments. If the sampled current falls below the threshold before the counter overflows, the counter is reset. Once the overcurrent counter reaches 2, the regulator shuts down.

After the regulator shuts down, it enters a delay interval equivalent to the soft-start interval, which allows the device to cool. The overcurrent counter is reset entering the delay interval. The protection logic initiates a normal soft-start once the delay interval ends. If the output successfully soft-starts, the power-good signal goes high and normal operation continues. If overcurrent conditions continue to exist during the soft-start interval, the overcurrent counter must overflow before the regulator shut downs the output again. This hiccup mode continues indefinitely until the output soft-starts successfully.

Component Selection Guide

This design guide is intended to provide a high-level explanation of the steps necessary to create a power converter. It is assumed the reader is familiar with many of the basic skills and techniques referenced in the following. In addition to this guide, Intersil provides a complete evaluation board that includes schematic, BOM, and an example PCB layout.

Output Filter Design

The output inductor and the output capacitor bank together to form a low-pass filter responsible for smoothing the pulsating voltage at the phase node. The filter must also provide the transient energy until the regulator can respond. Since the filter has low bandwidth relative to the switching frequency, it limits the system transient response. The output capacitors must supply or sink current while the current in the output inductor increases or decreases to meet the load demand.

OUTPUT CAPACITOR SELECTION

The critical load parameters in choosing the output capacitors are the maximum size of the load step (ΔI_{STEP}), the load-current slew rate (di/dt), and the maximum allowable output voltage deviation under transient loading (ΔV_{MAX}). Capacitors are characterized according to their capacitance, ESR (Equivalent Series Resistance) and ESL (Equivalent Series Inductance).

At the beginning of a load transient, the output capacitors supply all of the transient current. The output voltage will initially deviate by an amount approximated by the voltage drop across the ESL. As the load current increases, the voltage drop across the ESR increases linearly until the load current reaches its final value. Neglecting the contribution of inductor current and regulator response, the output voltage initially deviates by an amount shown in [Equation 8](#).

$$\Delta V_{MAX} \approx \left[ESL \times \frac{di}{dt} \right] + [ESR \times \Delta I_{STEP}] \quad (\text{EQ. 8})$$

The filter capacitors selected must have sufficiently low ESL and ESR such that the total output voltage deviation is less than the maximum allowable ripple.

Most capacitor solutions rely on a mixture of high frequency capacitors with relatively low capacitance in combination with bulk capacitors having high capacitance but larger ESR. Minimizing the ESL of the high-frequency capacitors, allows them to support the output voltage as the current increases. Minimizing the ESR of the bulk capacitors allows them to supply the increased current with less output voltage deviation.

Ceramic capacitors with X7R dielectric are recommended. Alternately, a combination of low ESR solid tantalum capacitors and ceramic capacitors with X7R dielectric may be used.

The ESR of the bulk capacitors is responsible for most of the output voltage ripple. As the bulk capacitors sink and source the inductor AC ripple current, a voltage, $V_{P-P(MAX)}$, develops across the bulk capacitor according to [Equation 9](#).

$$V_{P-P(MAX)} = ESR \times \left[\frac{(V_{IN} - V_{OUT})V_{OUT}}{L_{OUT} \times f_s \times V_{IN}} \right] \quad (\text{EQ. 9})$$

OUTPUT INDUCTOR SELECTION

Once the output capacitors are selected, the maximum allowable ripple voltage, $V_{P-P(MAX)}$, determines the lower limit on the inductance as shown in [Equation 10](#).

$$L_{OUT} \geq ESR \times \left[\frac{(V_{IN} - V_{OUT})V_{OUT}}{f_s \times V_{IN} \times V_{P-P(MAX)}} \right] \quad (\text{EQ. 10})$$

Since the output capacitors are supplying a decreasing portion of the load current while the regulator recovers from the transient, the capacitor voltage becomes slightly depleted. The output inductor must be capable of assuming the entire load current before the output voltage decreases more than ΔV_{MAX} . This places an upper limit on inductance.

[Equation 11](#) gives the upper limit on output inductance for the case when the trailing edge of the current transient causes the greater output voltage deviation than the leading edge.

[Equation 12](#) addresses the leading edge. Normally, the trailing edge dictates the inductance selection because duty cycles are usually <50%. Nevertheless, both inequalities should be evaluated, and inductance should be governed based on the lower of the two results. In each equation, L_{OUT} is the output inductance, C_{OUT} is the total output capacitance and $\Delta I_{L(P-P)}$ is the peak-to-peak ripple current in the output inductor.

$$L_{OUT} \leq \frac{2 \cdot C_{OUT} \cdot V_{OUT}}{(\Delta I_{STEP})^2} \left[\Delta V_{MAX} - (\Delta I_{L(P-P)} \cdot ESR) \right] \quad (\text{EQ. 11})$$

$$L_{OUT} \leq \frac{2 \cdot C_{OUT}}{(\Delta I_{STEP})^2} \left[\Delta V_{MAX} - (\Delta I_{L(P-P)} \cdot ESR) \right] (V_{IN} - V_{OUT}) \quad (\text{EQ. 12})$$

The other concern when selecting an output inductor is to insure there is adequate slope compensation when the regulator is operated above 40% duty cycle. In most cases, the maximum slope compensation setting (SC1 = DVDD, SC0 = DVDD) provides sufficient phase margin, therefore this is the recommended configuration.

Input Capacitor Selection

Input capacitors are responsible for sourcing the AC component of the input current flowing into the switching power devices. Their RMS current capacity must be sufficient to handle the AC component of the current drawn by the switching power devices, which is related to duty cycle. The maximum RMS current required by the regulator is closely approximated by [Equation 13](#).

$$I_{RMS} = I_{OUT} \times \sqrt{\frac{V_{OUT}}{V_{IN}}} \sqrt{1 + \frac{1}{3} \times \left(\frac{V_{IN} - V_{OUT}}{I_{OUT} \times L_{OUT} \times f_s} \times \frac{V_{OUT}}{V_{IN}} \right)^2} \quad (\text{EQ. 13})$$

The important parameters to consider when selecting an input capacitor are the voltage rating and the RMS ripple current rating. For reliable operation, select capacitors with voltage ratings at least 1.5x greater than the maximum input voltage. The capacitor RMS ripple current rating should be higher than the largest RMS ripple current required by the circuit.

A combination of low ESR tantalum capacitors and ceramic capacitors with X7R dielectric are recommended. The ISL70002SEH requires a minimum effective input capacitance of 100 μ F for stable operation.

PCB Design

PCB design is critical to high-frequency switching regulator performance. Careful component placement and trace routing are necessary to reduce voltage spikes and minimize undesirable voltage drops. Selection of a suitable thermal interface material is also required for optimum heat dissipation and to provide lead strain relief.

PCB Plane Allocation

Four layers of 2-oz. copper are recommended. Layer 2 should be a dedicated ground plane with all critical component ground connections made with vias to this layer. Layer 3 should be a dedicated power plane split between the input and output power rails. Layers 1 and 4 should be used primarily for signals, but can also provide additional power and ground islands as required.

PCB Component Placement

Components should be placed as close as possible to the IC to minimize stray inductance and resistance. Prioritize the placement of bypass capacitors on the pins of the IC in the order shown: REF, SS, AVDD, DVDD, PVINx (high frequency capacitors), EN, PGOOD, PVINx (bulk capacitors).

Locate the output voltage resistive divider as close as possible to the FB pin of the IC. The top leg of the divider should connect directly to the POL (Point Of Load) and the bottom leg of the divider should connect directly to AGND. The junction of the resistive divider should connect directly to the FB pin.

A small series R-C snubber connected from the LXx pins to the PGNDx pins may be used to damp high frequency ringing on the LXx pins if desired.

PCB Layout

Use a small island of copper to connect the LXx pins of the IC to the output inductor on layers 1 and 4. To minimize capacitive coupling to the power and ground planes, void the copper on layers 2 and 3 adjacent to the island. Place most of the island of layer 4 to minimize the amount of copper that must be voided from the ground plane (layer 2).

Keep all other signal traces as short as possible.

For an example layout refer to [AN1732](#).

Thermal Management for Ceramic Package

For optimum thermal performance, place a pattern of vias on the top layer of the PCB directly underneath the IC. Connect the vias to the plane which serves as a heatsink. To ensure good thermal contact, thermal interface material such as a Sil-Pad or thermally conductive epoxy should be used to fill the gap between the vias and the bottom of the IC of the ceramic package.

Lead Strain Relief

The package leads protrude from the bottom of the package and the leads need forming to provide strain relief. On the ceramic bottom package R64.A, the Sil-pad or epoxy maybe be used to fill the gap left between the PCB board and the bottom of the package when lead forming is completed. On the heatsink option of the package R64.C, the lead forming should be made so that the bottom of the heatsink and the formed leads are flush.

Heatsink Mounting Guidelines

The R64.C package option has a heatsink mounted on the underside of the package. The following JESD-51x series guidelines may be used to mount the package:

1. Place a thermal land on the PCB under the heatsink.
2. The land should be approximately the same size as to 1mm larger than the 10.16x10.16mm heatsink.
3. Place an array of thermal vias below the thermal land.
 - Via array size: $\sim 9 \times 9 = 81$ thermal vias.
 - Via diameter: ~ 0.3 mm drill diameter with plated copper on the inside of each via.
 - Via pitch: ~ 1.2 mm.
 - Vias should drop to and contact as much buried metal area as feasible to provide the best thermal relief.

Heatsink Electrical Potential

The heatsink is connected to pin 50 within the package; thus the PCB design and potential applied to pin 50 will therefore define the heatsink potential.

Heatsink Mounting Materials

In the case of electrically conductive mounting methods (conductive epoxy, solder, etc) the thermal land, vias and connected plane(s) below must be the same potential as pin 50.

In the case of electrically nonconductive mounting methods (nonconductive epoxy), the heatsink and pin 50 could have different electrical potential than the thermal land, vias and connected plane(s) shown in following.

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Weight Characteristics

Weight of Packaged Device

- 1.43 grams typical - R64.A Package
- 2.65 grams typical - R64.C Package

Die Characteristics

Die Dimensions

- 8300µm x 8300µm (327 mils x 327 mils)
- Thickness: 300µm ± 25.4µm (12 mils ± 1 mil)

Interface Materials

GLASSIVATION

- Type: Silicon Oxide and Silicon Nitride
- Thickness: 0.3µm ± 0.03µm and 1.2µm ± 0.12µm

TOP METALLIZATION

- Type: AlCu (0.5%)
- Thickness: 2.7µm ± 0.4µm

SUBSTRATE

- Type: Silicon
- Isolation: Junction

BACKSIDE FINISH

- Silicon

ASSEMBLY RELATED INFORMATION

Substrate and Metal Lid Potential

- PGND

Heatsink Potential R64.C Package

- Connected to Pin 50, Electrically Isolated

ADDITIONAL INFORMATION

Worst Case Current Density

- $< 2 \times 10^5 \text{ A/cm}^2$

Transistor Count

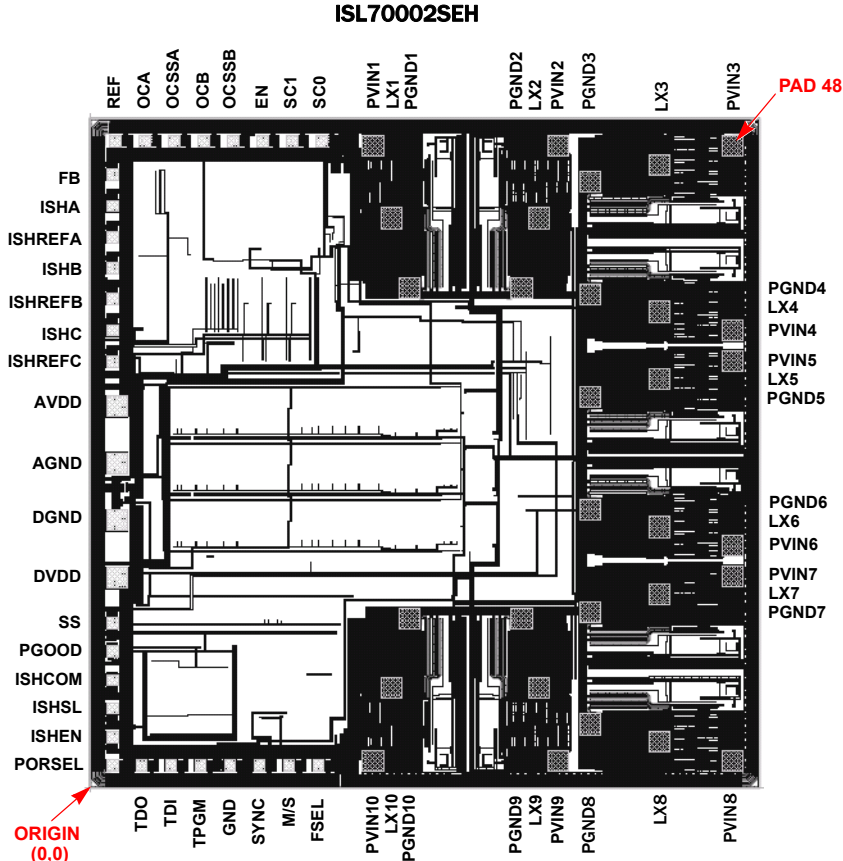
- 28,160

Layout Characteristics

Step and Repeat

- 8300µm x 8300µm

Metallization Mask Layout



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TABLE 2. LAYOUT X-Y COORDINATES

| PAD NAME | PAD NUMBER | X (μm) | Y (μm) | dX (μm) | dY (μm) | BOND WIRES SIZE (0.001") |
|----------|------------|--------|--------|---------|---------|--------------------------|
| FB | 1 | 275 | 7497 | 135 | 135 | 1.5 |
| ISHA | 2 | 275 | 7117 | 135 | 135 | 1.5 |
| ISHREFA | 3 | 275 | 6737 | 135 | 135 | 1.5 |
| ISHB | 4 | 275 | 6357 | 135 | 135 | 1.5 |
| ISHREFB | 5 | 275 | 5977 | 135 | 135 | 1.5 |
| ISHC | 6 | 275 | 5597 | 135 | 135 | 1.5 |
| ISHREFC | 7 | 275 | 5217 | 135 | 135 | 1.5 |
| AVDD | 8 | 335 | 4672 | 254 | 254 | 3 |
| AGND | 9 | 335 | 3972 | 254 | 254 | 3 |
| DGND | 10 | 335 | 3272 | 254 | 254 | 3 |
| DVDD | 11 | 335 | 2572 | 254 | 254 | 3 |
| SS | 12 | 275 | 2021 | 135 | 134 | 1.5 |
| PGOOD | 13 | 275 | 1671 | 135 | 135 | 1.5 |
| ISHCOM | 14 | 275 | 1321 | 135 | 135 | 1.5 |
| ISHSL | 15 | 275 | 971 | 135 | 135 | 1.5 |
| ISHEN | 16 | 275 | 621 | 135 | 135 | 1.5 |
| PORSEL | 17 | 275 | 275 | 135 | 135 | 1.5 |
| TDO | 18 | 635 | 275 | 135 | 135 | 1.5 |
| TDI | 19 | 995 | 275 | 135 | 135 | 1.5 |
| TPGM | 20 | 1355 | 275 | 135 | 135 | 1.5 |
| GND | 21 | 1715 | 275 | 135 | 135 | 1.5 |
| SYNC | 22 | 2075 | 275 | 135 | 135 | 1.5 |
| M/S | 23 | 2435 | 275 | 135 | 135 | 1.5 |
| FSEL | 24 | 2795 | 275 | 135 | 135 | 1.5 |
| PVIN10 | 25 | 3463 | 336 | 254 | 254 | 3 |
| LX10 | 26 | 3693 | 1222 | 254 | 254 | 3 |
| PGND10 | 27 | 3905 | 2074 | 254 | 254 | 3 |
| PGND9 | 28 | 5281 | 2074 | 254 | 254 | 3 |
| LX9 | 29 | 5494 | 1222 | 254 | 254 | 3 |
| PVIN9 | 30 | 5723 | 336 | 254 | 254 | 3 |
| PGND8 | 31 | 6115 | 778 | 254 | 254 | 3 |
| LX8 | 32 | 6967 | 566 | 254 | 254 | 3 |
| PVIN8 | 33 | 7853 | 336 | 254 | 254 | 3 |
| PGND7 | 34 | 6115 | 2154 | 254 | 254 | 3 |
| LX7 | 35 | 6967 | 2366 | 254 | 254 | 3 |
| PVIN7 | 36 | 7853 | 2596 | 254 | 254 | 3 |
| PVIN6 | 37 | 7853 | 2965 | 254 | 254 | 3 |
| LX6 | 38 | 6967 | 3195 | 254 | 254 | 3 |
| PGND6 | 39 | 6115 | 3408 | 254 | 254 | 3 |

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TABLE 2. LAYOUT X-Y COORDINATES (Continued)

| PAD NAME | PAD NUMBER | X (μm) | Y (μm) | dX (μm) | dY (μm) | BOND WIRES SIZE (0.001") |
|----------|------------|------------------------|------------------------|-------------------------|-------------------------|-----------------------------|
| PGND5 | 40 | 6115 | 4784 | 254 | 254 | 3 |
| LX5 | 41 | 6967 | 4996 | 254 | 254 | 3 |
| PVIN5 | 42 | 7853 | 5226 | 254 | 254 | 3 |
| PVIN4 | 43 | 7853 | 5595 | 254 | 254 | 3 |
| LX4 | 44 | 6967 | 5825 | 254 | 254 | 3 |
| PGND4 | 45 | 6115 | 6037 | 254 | 254 | 3 |
| PGND3 | 46 | 6115 | 7413 | 254 | 254 | 3 |
| LX3 | 47 | 6967 | 7625 | 254 | 254 | 3 |
| PVIN3 | 48 | 7853 | 7855 | 254 | 254 | 3 |
| PVIN2 | 49 | 5723 | 7855 | 254 | 254 | 3 |
| LX2 | 50 | 5494 | 6969 | 254 | 254 | 3 |
| PGND2 | 51 | 5281 | 6117 | 254 | 254 | 3 |
| PGND1 | 52 | 3905 | 6117 | 254 | 254 | 3 |
| LX1 | 53 | 3693 | 6969 | 254 | 254 | 3 |
| PVIN1 | 54 | 3463 | 7855 | 254 | 254 | 3 |
| SC0 | 55 | 2836 | 7914 | 135 | 135 | 1.5 |
| SC1 | 56 | 2476 | 7914 | 135 | 135 | 1.5 |
| EN | 57 | 2116 | 7914 | 135 | 135 | 1.5 |
| OCSSB | 58 | 1756 | 7914 | 135 | 135 | 1.5 |
| OCB | 59 | 1396 | 7914 | 135 | 135 | 1.5 |
| OCSSA | 60 | 1036 | 7914 | 135 | 135 | 1.5 |
| OCA | 61 | 676 | 7914 | 135 | 135 | 1.5 |
| REF | 62 | 316 | 7914 | 135 | 135 | 1.5 |

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Revision History

The revision history provided is for informational purposes only and is believed to be accurate, but not warranted. Please go to web to make sure you have the latest revision.

| DATE | REVISION | CHANGE |
|-------------------|----------|---|
| October 1, 2015 | FN8264.8 | On page 20 in "Metallization Mask Layout", clarified pad labels for PVIN3, LX8, PGND3, PVIN8, LX8, PGND8. Corrected XY coordinates for PVIN3, PGND3, PVIN8, PGND8 in Table 2 on page 21. |
| October 9, 2014 | FN8264.7 | On "EFFICIENCY 5V INPUT, 500kHz, Tcase = +25°C" on page 1: changed Figure 1 to reflect latest testing results. Pin descriptions on page 6: Clarified pin descriptions for pins 60 through 63. Figures 4 and 5 on pages 7 and 8 corrected pin numbers for PVINx, LXx AND PGNDx. |
| July 11, 2014 | FN8264.6 | Absolute Maximum Ratings on page 9 : updated Heading by adding " Ratings in a Heavy Ion Environment". Absolute Maximum Ratings on page 9 : added: Absolute Maximum Ratings without Heavy Ions values to the table section. |
| May 20, 2014 | FN8264.5 | Page 1: Added Related Literature, Updated bullets under Features section as below: <ul style="list-style-type: none"> From "12A output current for a single device (at TJ = +150°C)" to "Output current for a single device 14A at TJ = +125°C; 12A at TJ = +150°C" From "• 14A output current for a single device (at TJ = +125°C) • 19A output current for two paralleled devices" to "Output current for two paralleled devices 22A at TJ = +125°C; 19A at TJ = +150°C" |
| February 11, 2014 | FN8264.4 | On page 3 modified the pin configuration diagram to explicitly identify PIN 1. Updated POD R64.A from Rev 4 to Rev 5 to show larger corner chamfer in pin #16/17 corner. Updated POD R64.C from Rev 0 to Rev 1 to show larger corner chamfer in pin #16/17 corner. "Switching Frequency and Synchronization" on page 15 - Added text to third paragraph. |
| July 12, 2013 | FN8264.3 | On page 3 modified the pin configuration, and changed note from indicates changes heatsink package R64.C to indicates heatsink package R64.C. On page 4 modified pin 50 description from: ..."the heatsink to the power plane which offers the best thermal relief", to...."the heatsink to a thermal plane". Made correction to Equations in pin description table on page 6 matching SMD for pins 60, 62 and 61, 63. |
| June 10, 2013 | FN8264.2 | On page 1: Added bullet, "14A output current for a single device (at TJ = +125°C)" to Feature list. Ordering information table on page 3: Added new part number ISL70002SEHFE and ISL70002SEHFE/PROTO. Thermal Information table on page 9: Added CQFP Package R64.C $\theta_{JA}17$, $\theta_{JC}0.7$. Ordering information table on page 3: Added R46.C package outline drawing. Added POD "R46.C" to datasheet. |
| May 7, 2013 | FN8264.1 | Added the heatsink package option to the ordering table. Also added mounting guidelines, electrical potential and mounting material sections to the datasheet. |
| March 30, 2012 | FN8264.1 | Figure 2 on page 1 changed "Slave" to "Master" to CH1 and added "at 86.4MeV/mg/cm2" to Figure Title. "Soft-Start" on page 16 changed in 2nd to last sentence "...range from 8.2nF..." to "...range from 82nF..." "LAYOUT X-Y COORDINATES" on page 21 changed in Bond Wires column for "ISHB" from "1.51" to "1.5" |
| March 27, 2012 | FN8264.0 | Initial Release |

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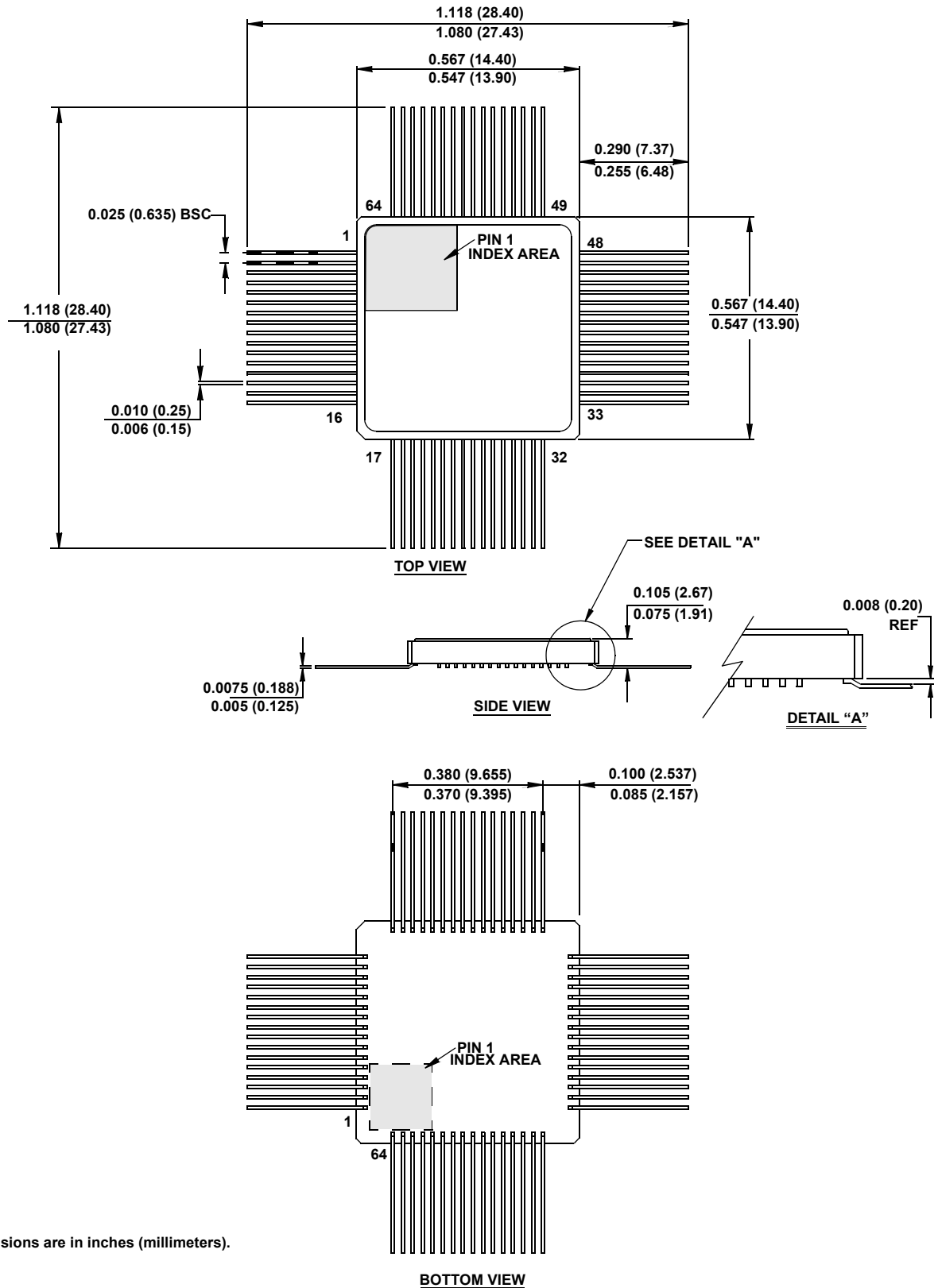
ISL70002SEH

Package Outline Drawing

R64.A

64 CERAMIC QUAD FLATPACK PACKAGE (CQFP)

Rev 5, 10/13



Package Outline Drawing

R64.C

64 CERAMIC QUAD FLATPACK PACKAGE (CQFP) WITH BOTTOM HEATSINK

Rev 1, 10/13

